SP2996B



2 Amp DDR Bus Termination Regulator

Rev. 2.0.0

GENERAL DESCRIPTION

The SP2996B voltage regulator is designed to convert voltage supplies ranging from 1.6V to 6V into a desired output voltage which is adjusted by an external resistor divider.

The regulator is capable of sourcing or sinking up to 2A of Continuous current while regulating an output voltage to within 20mV. The SP2996B provides an excellent voltage source for active termination schemes of high speed transmission lines such as those seen in high speed memory buses and distributed backplane designs when used in conjunction with series termination resistors. The voltage output of the regulator can be used as a termination voltage for DDR SDRAM, and it meets the JEDEC SSTL-2 and SSTL-3 specifications. Current limits in both sourcing and sinking mode, plus on-chip thermal shutdown make the circuit tolerant of output fault conditions.

APPLICATIONS

- DDR Memory Termination
- Active Bus Termination
- Supply Splitter

FEATURES

- Capable of Sourcing and sinking 2A Continuous Current
- Supports both DDR1 (1.25V_{TT}) and DDR2 (0.9V_{TT}) Requirements
- Low Output Voltage Offset, ± 20mV
- Thermal and Current Limit Protection
- Integrated Power MOSFETs
- Generates Termination for SSTL-2
- High Accuracy Output at Full Load
- Adjustable V_{OUT} by External Resistors
- Minimal External Components
- Available in 8-Pin NSOIC Package



TYPICAL APPLICATION DIAGRAM

Fig. 1: SP2996B Application Diagram



ABSOLUTE MAXIMUM RATINGS

These are stress ratings only and functional operation of the device at these ratings or any other above those indicated in the operation sections of the specifications below is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

Supply Voltage	0.3V to 7.0V
Junction Temperature Range	40°C to +125°C
Storage Temperature	65°C to 150°C

ELECTRICAL SPECIFICATIONS

OPERATING RATINGS

Operating Temperature Range	-40°C to +85°C
Thermal Resistance θ_{JA}	160°C/W
Thermal Resistance $\theta_{\mbox{\tiny JC}}$	40°C/W

Specifications with standard type are for an Operating Ambient Temperature of $T_A = 25^{\circ}C$ only; limits applying over the full Operating Junction Temperature range are denoted by a "•". Minimum and Maximum limits are guaranteed through test, design, or statistical correlation. Typical values represent the most likely parametric norm at $T_A = 25^{\circ}C$, and are provided for reference purposes only. Unless otherwise indicated, $V_{IN} = 2.5V$, $V_{CNTL} = 3.3V$, $V_{REF} = 0.5xV_{IN}$, $C_{OUT} = 10\mu$ F (ceramic), $T_A = 25^{\circ}C$.

Parameter	Min.	Тур.	Max.	Units		Conditions	
Input Voltage Range (DDR 1/2) V_{IN}	1.6	2.5/1.8		V	a ((note 4) Keep $V_{CNTL} \ge V_{IN}$ on operation power on and power off sequences	
Input Voltage Range (DDR 1/2) V_{CNTL}	3.0	3.3	3.6	V	(I	(note 4) I _{OUT} = 0mA	
Output Voltage V _{OUT}		V_{REF}		V	I	$I_{OUT} = 0 m A$	
Output Offset Voltage V _{os}	-20		+20	mV	Ν	No load	
Load Regulation (DDR 1/2) AV		10	25	mV	I	$I_{OUT} = 0.1 \text{mA to } + 2 \text{A}$	
Load Regulation (DDR 1/2) ΔV_{LOR}		10	25	mV	I	$I_{OUT} = 0.1 \text{mA to } -2 \text{A}$	
Quiescent Current I _Q		8	30	μA	l l	$V_{REF} < 0.2V, V_{OUT} = OFF$	
Operating Current of V_{CNTL} , I_{CNTL}		3	10	mA	Ν	No load	
Bias Current of V _{REF}			1	μA	l l	$V_{REF} = 1.25V$	
Current Limit I_{IL}	2.2	3	4.5	Α	((note 3)	
Thermal Protection							
Thermal Shutdown Temperature T _{SD}	125	150		°C	(3	(note 4) 3.3V \leq V _{CNTL} \leq 5V, guaranteed by design	
Thermal Shutdown Hysteresis		30		°C	0	Guaranteed by design	
Shutdown Specifications							
	0.8			- V -		Dutput ON $V_{\text{REF}} = 0V \rightarrow 1.25V$	
			0.2			Dutput OFF $J_{REF} = 1.25V \rightarrow 0V$	

Note 1: V_{OS} offset is the voltage measurement defined as V_{OUT} subtracted from V_{REF} .

Note 2: Load regulation is measured at constant junction temperature, using pulse testing with a low ON time.

Note 3: Current limit is measured by pulsing a short time.

Note 4: In order to safely operate your system, V_{CNTL} must be > V_{IN} .



BLOCK DIAGRAM



Fig. 2: SP2996B Block Diagram

PIN ASSIGNMENT



Fig. 3: SP2996B Pin Assignment

PIN DESCRIPTION

Name	Pin Number	Description		
V _{IN}	1	Power Input Voltage		
GND	2	Ground Signal		
V _{REF}	3	Reference Input Voltage. This input can also be used as an enable signal. Refer to typical application circuit.		
V _{OUT}	4	Jutput Voltage		
V _{CNTL}	5			
V _{CNTL}	6	Voltage for the driver circuit and all analog blocks		
V _{CNTL}	7			
V _{CNTL}	8			

ORDERING INFORMATION

Part Number	Temperature Range	Marking	Package	Packing Quantity	Note 1	Note 2
SP2996BEN-L	-40°C≤T _A ≤+85°C	SP2996BE YYWWL X	SOIC-8	Bulk	Lead Free	
SP2996BEN-L/TR	-40°C≤T _A ≤+85°C	SP2996BE YYWWL X	SOIC-8	2.5K/Tape & Reel	Lead Free	

"YY" = Year - "WW" = Work Week - "L" = Lead Free Indicator - "X" = Lot Number; when applicable.



TYPICAL PERFORMANCE CHARACTERISTICS

All data taken at $V_{IN} = 2.5V$, $V_{CNTL} = 3.3V$, $V_{REF} = 0.5xV_{IN}$, $C_{OUT} = 10\mu F$ (ceramic), $T_A = 25^{\circ}C$, unless otherwise specified - Schematic and BOM from Application Information section of this datasheet.



Fig. 4: Turn-on Threshold vs Temperature



Fig. 5: Turn-on Threshold vs Temperature



Fig. 6: Sinking Current (Peak) vs Temperature



Fig. 8: Output Offset Voltage vs Temperature



Fig. 7: Sourcing Current (Peak) vs Temperature













Fig. 11: Transient Response @ $1.25V_{\rm TT}/2A$



2 Amp DDR Bus Termination Regulator

APPLICATION INFORMATION

INTERNAL PARASITIC DIODE

Avoid forward-biasing the internal parasitic diode, V_{OUT} to V_{CNTL} , and V_{OUT} to V_{IN} . Positive voltage should not be applied to the output if V_{IN} and V_{CNTL} are not present.

CONSIDERATIONS FOR DESIGNING, RESISTANCE OF VOLTAGE DIVIDER

When the reference voltage is programmed below 0.2V the pulldown capability of the internal NMOS transistor is limited. It is recommened to place a filter capacitor from V_{REF} to ground in order to reduce sensitivity to

noise and improve power up characteristics (soft start).

LAYOUT CONSIDERATIONS

The SP2996B is offered in the NSOIC-8 package, resulting in attention needing to be paid to dissipating heat effectively when it operates in high current. In order to prevent maximum junction temperature from being exceeded, suitable copper area is necessary. The large copper area at VCNTL pins is available, and by taking advantage of this, much heat dissipation is attained. Use vias to direct heat into the bottom layer as the layout examples show below. All capacitors should be placed as close as possible to relative pins.

TEST CIRCUITS

Testing Output Voltage Tolerance ΔV_{LOAD}



Testing Current in Shutdown Mode I_{SHDN}





Testing Current Limit for High Side $\mathbf{I}_{\text{LIMIT}}$



Testing Current Limit for Low Side $\mathbf{I}_{\text{Limit}}$



Testing V_{REF} Pin Shutdown Threshold V_{TRIGGER}





PACKAGE SPECIFICATION

8-PIN NSOIC







8 Pin NSOIC JEDEC MS			S-012	Variation	AA	
SYMBOL	Dimensions in Millimeters: Controlling Dimension			Dimensions in Inches Conversion Factor: 1 Inch = 25.40 mm		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.35	-	1.75	0.053	-	0.069
A1	0.10	-	0.25	0.004	-	0.010
A2	1.25	-	1.65	0.049	-	0.065
b	0.31	-	0.51	0.012	-	0.020
с	0.17	-	0.25	0.007	-	0.010
E	6.00 BSC			0.236 BSC		
E1		3.90 BSC		0.154 BSC		
е	1.27 BSC			0.050 BSC		
h	0.25		0.50	0.010	-	0.020
L	0.40	-	1.27	0.016	-	0.050
L1	1.04 REF			0.041 REF		
L2		0.25 BSC	_	0.010 BSC		
R	0.07	-	-	0.003	-	-
R1	0.07	-	-	0.003	-	-
ø	00	-	80	00	-	80
ø1	50	-	15°	50	-	15°
ø2	00	-	-	00	-	-
Ď		4.90 BSC		0.193 BSC		
SIPEX Pkg Signoff Date/Rev:				J	L Aug16-05 / F	Rev A



REVISION HISTORY

Revision	Date	Description
2.0.0	09/27/2010	Reformat of data sheet Corrected V _{CTRL} vs V _{CNTL} and V _{REF} annotations

FOR FURTHER ASSISTANCE

Email:

Exar Technical Documentation:

customersupport@exar.com http://www.exar.com/TechDoc/default.aspx?



EXAR CORPORATION

HEADQUARTERS AND SALES OFFICES

48720 Kato Road Fremont, CA 94538 – USA Tel.: +1 (510) 668-7000 Fax: +1 (510) 668-7030 www.exar.com

NOTICE

EXAR Corporation reserves the right to make changes to the products contained in this publication in order to improve design, performance or reliability. EXAR Corporation assumes no responsibility for the use of any circuits described herein, conveys no license under any patent or other right, and makes no representation that the circuits are free of patent infringement. Charts and schedules contained here in are only for illustration purposes and may vary depending upon a user's specific application. While the information in this publication has been carefully checked; no responsibility, however, is assumed for inaccuracies.

EXAR Corporation does not recommend the use of any of its products in life support applications where the failure or malfunction of the product can reasonably be expected to cause failure of the life support system or to significantly affect its safety or effectiveness. Products are not authorized for use in such applications unless EXAR Corporation receives, in writing, assurances to its satisfaction that: (a) the risk of injury or damage has been minimized; (b) the user assumes all such risks; (c) potential liability of EXAR Corporation is adequately protected under the circumstances.

Reproduction, in part or whole, without the prior written consent of EXAR Corporation is prohibited.